

Title (en)
HOT STAMPING MATERIAL AND PRODUCTION METHOD THEREFOR

Title (de)
HEISSPRÄGEMATERIAL UND VERFAHREN ZU SEINER HERSTELLUNG

Title (fr)
MATÉRIAU D'ESTAMPAGE À CHAUD ET PROCÉDÉ DE FABRICATION ASSOCIÉ

Publication
EP 4209610 A1 20230712 (EN)

Application
EP 21806609 A 20210608

Priority
• KR 20200111293 A 20200901
• KR 20210042812 A 20210401
• KR 2021007161 W 20210608

Abstract (en)
Provided are a material for hot stamping, wherein the material includes: a steel sheet including carbon (C) in about 0.28 wt% to about 0.50 wt%, silicon (Si) in about 0.15 wt% to about 0.70 wt%, manganese (Mn) in about 0.5 wt% to about 2.0 wt%, phosphorus (P) less than or equal to 0.05 wt%, sulfur (S) less than or equal to 0.01 wt%, chromium (Cr) of about 0.1 wt% to about 0.5 wt%, boron (B) in about 0.001 wt% to about 0.005 wt%, an additive less than or equal to 0.1 wt%, balance iron (Fe), and other inevitable impurities; and fine precipitates distributed within the steel sheet, wherein the additive includes at least one of titanium (Ti), niobium (Nb), and vanadium (V), and the fine precipitates include nitride or carbide of at least one of titanium (Ti), niobium (Nb), and vanadium (V), and trap hydrogen.

IPC 8 full level
C22C 38/38 (2006.01); **B21B 1/26** (2006.01); **B21D 22/02** (2006.01); **C21D 8/02** (2006.01); **C21D 9/46** (2006.01); **C22C 38/00** (2006.01); **C22C 38/26** (2006.01); **C22C 38/28** (2006.01)

CPC (source: CN EP US)
B21B 1/26 (2013.01 - CN US); **C21D 1/02** (2013.01 - EP); **C21D 6/002** (2013.01 - US); **C21D 6/005** (2013.01 - US); **C21D 6/008** (2013.01 - US); **C21D 6/02** (2013.01 - US); **C21D 8/0205** (2013.01 - EP US); **C21D 8/021** (2013.01 - EP); **C21D 8/0226** (2013.01 - CN EP US); **C21D 8/0242** (2013.01 - CN); **C21D 9/46** (2013.01 - EP US); **C22C 38/002** (2013.01 - US); **C22C 38/02** (2013.01 - CN EP US); **C22C 38/04** (2013.01 - CN EP US); **C22C 38/24** (2013.01 - CN EP); **C22C 38/26** (2013.01 - CN EP); **C22C 38/28** (2013.01 - CN EP); **C22C 38/32** (2013.01 - CN EP US); **C22C 38/38** (2013.01 - CN EP); **B21D 22/022** (2013.01 - EP US); **C21D 8/0236** (2013.01 - EP); **C21D 8/0273** (2013.01 - EP); **C21D 2211/004** (2013.01 - EP US)

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

Designation validation state (EPC)
KH MA MD TN

DOCDB simple family (publication)
EP 4209610 A1 20230712; **EP 4209610 A4 20240117**; BR 112023003717 A2 20230328; CA 3190916 A1 20220310; CN 114466947 A 20220510; CN 114466947 B 20230523; JP 2023540210 A 20230922; MX 2023002518 A 20230313; US 2023265538 A1 20230824; WO 2022050536 A1 20220310

DOCDB simple family (application)
EP 21806609 A 20210608; BR 112023003717 A 20210608; CA 3190916 A 20210608; CN 202180003764 A 20210608; JP 2023512800 A 20210608; KR 2021007161 W 20210608; MX 2023002518 A 20210608; US 202318115528 A 20230228